

Features

- Trench Power MV MOSFET Technology
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant (Note2) ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

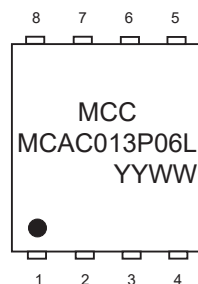
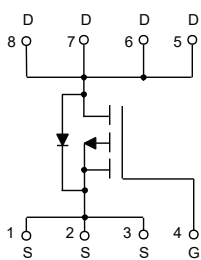
- Operating Junction Temperature Range : -55°C to +175°C
- Storage Temperature Range: -55°C to +175°C
- Thermal Resistance: 55°C/W Junction to Ambient (Note3)
- Thermal Resistance: 1°C/W Junction to Case

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	-60	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	I_D	$T_C=25^\circ\text{C}$	-74
		$T_C=100^\circ\text{C}$	-52
Pulsed Drain Current (Note4)	I_{DM}	-296	A
Total Power Dissipation (Note5)	P_D	150	W
Single Pulse Avalanche Energy (Note6)	E_{AS}	225	mJ

Note:

1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. High Temperature Solder Exemption Applied, see EU Directive Annex 7(a)-I.
3. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$.
4. Repetitive rating; pulse width limited by max. junction temperature.
5. P_D is based on max. junction temperature, using junction-case thermal resistance.
6. $T_J=25^\circ\text{C}$, $V_{DD}=-30\text{V}$, $V_{GS}=-10\text{V}$, $R_G=25\Omega$, $L=0.5\text{mH}$.

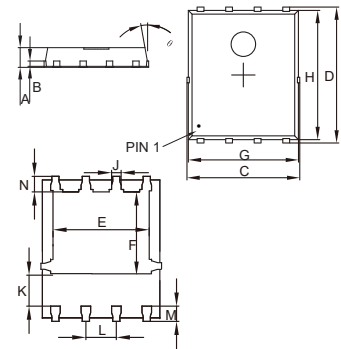
Internal Structure and Marking Code



4 codes in total
YY is the year
WW is the week

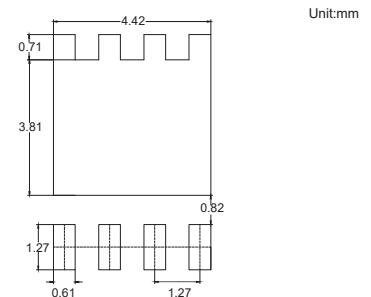
P-CHANNEL MOSFET

DFN5060



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.031	0.047	0.80	1.20	
B	0.010		0.254		TYP.
C	0.193	0.222	4.90	5.64	
D	0.232	0.250	5.90	6.35	
E	0.148	0.167	3.75	4.25	
F	0.126	0.154	3.20	3.92	
G	0.189	0.213	4.80	5.40	
H	0.222	0.239	5.65	6.06	
K	0.045	0.059	1.15	1.50	
J	0.012	0.020	0.30	0.50	
L	0.046	0.054	1.17	1.37	
M	0.012	0.028	0.30	0.71	
N	0.016	0.028	0.40	0.71	

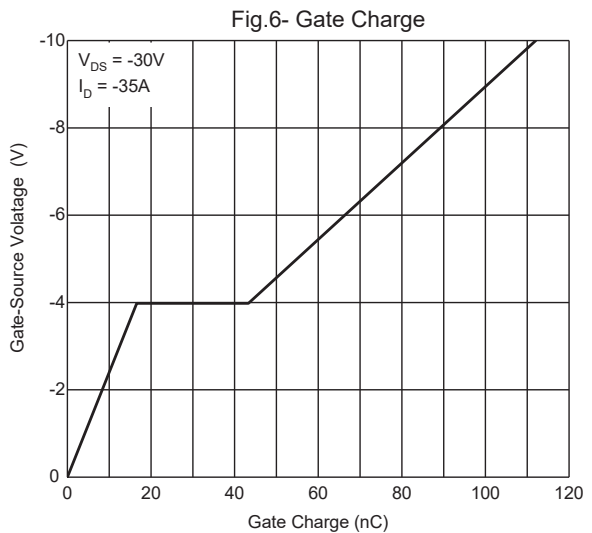
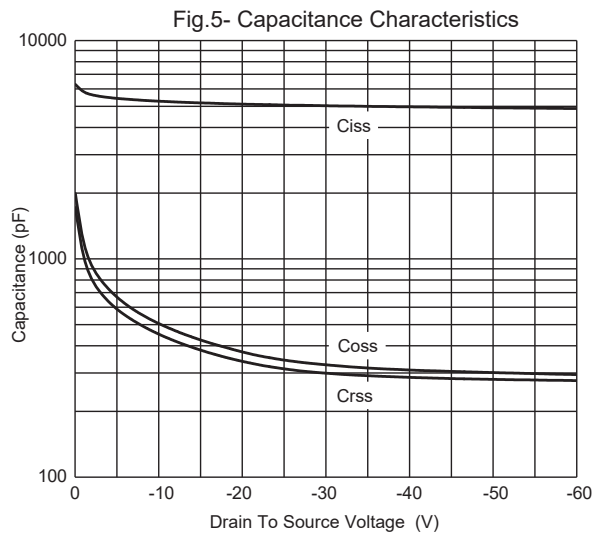
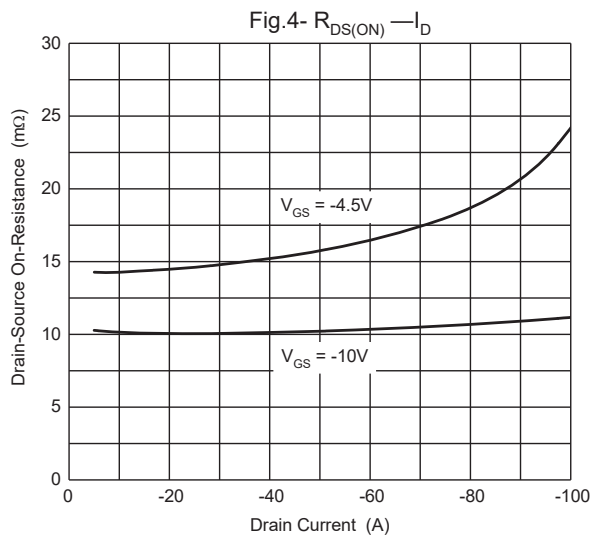
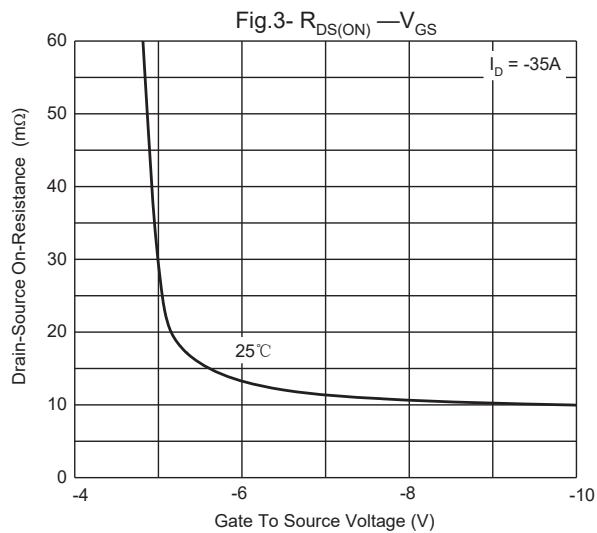
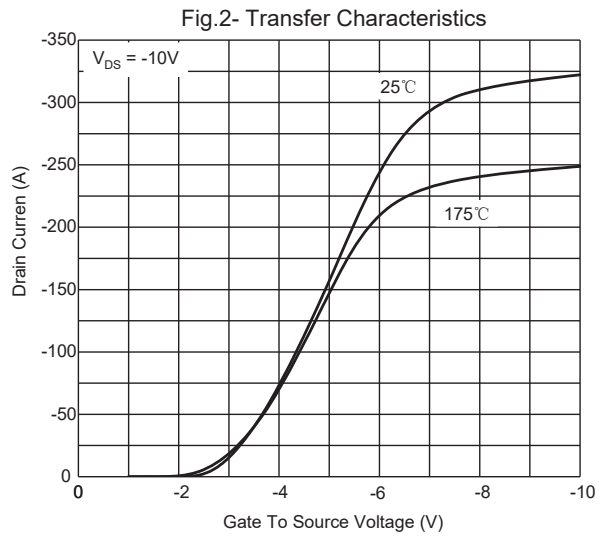
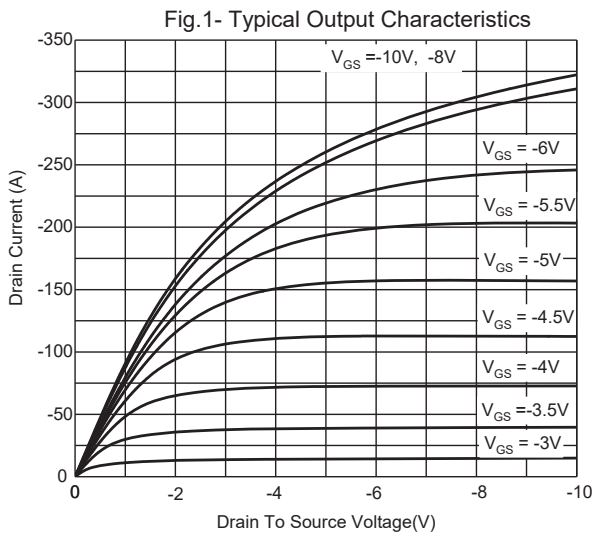
Suggested Solder Pad Layout



Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-60			V
Gate-Source Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-60V, V_{GS}=0V$			-1	μA
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.2	-1.8	-2.4	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-35A$		10	13	m Ω
		$V_{GS}=-4.5V, I_D=-20A$		14.5	22	
Gate Resistance	R_G	f=1 MHz, Open Drain		7		Ω
Diode Characteristics						
Continuous Body Diode Current	I_S				-74	A
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=-35A$			-1.2	V
Reverse Recovery Time	t_{rr}	$I_F=-35A, dI_F/dt=100A/\mu s$		28.4		ns
Reverse Recovery Charge	Q_{rr}			37.6		nC
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=-30V, V_{GS}=0V, f=1MHz$		5029		pF
Output Capacitance	C_{oss}			327		
Reverse Transfer Capacitance	C_{rss}			299		
Total Gate Charge	Q_g	$V_{DS}=-30V, V_{GS}=-10V, I_D=-35A$		112		nC
Gate-Source Charge	Q_{gs}			16.6		
Gate-Drain Charge	Q_{gd}			26.7		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=-30V, V_{GS}=-10V, R_G=3\Omega, I_{DS}=-35A$		12.6		ns
Turn-On Rise Time	t_r			36		
Turn-Off Delay Time	$t_{d(off)}$			150		
Turn-Off Fall Time	t_f			83		

Curve Characteristics



Curve Characteristics

Fig. 7 - Normalized Threshold Voltage

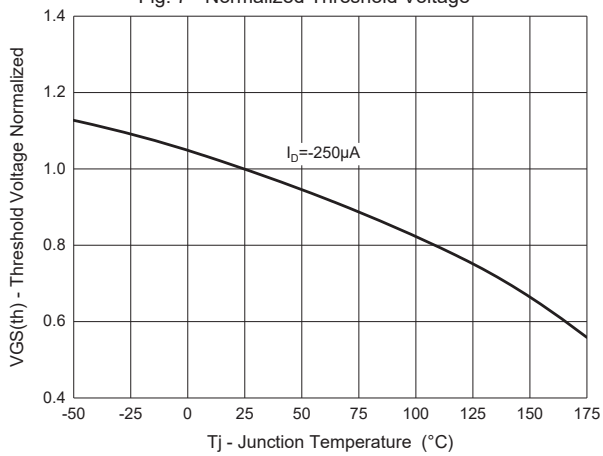


Fig. 8 - Normalized On Resistance Characteristics

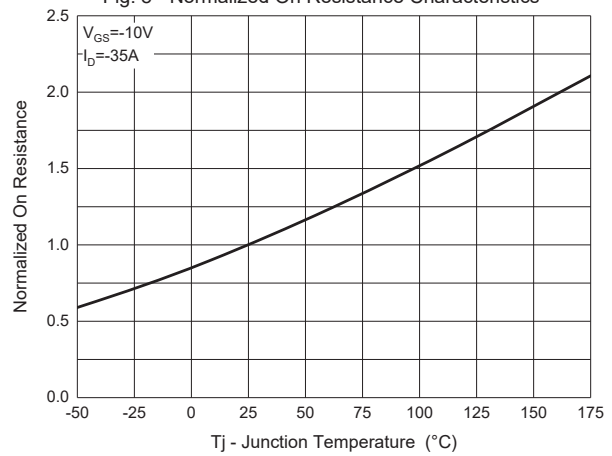


Fig. 9 - I_S-V_{SD}

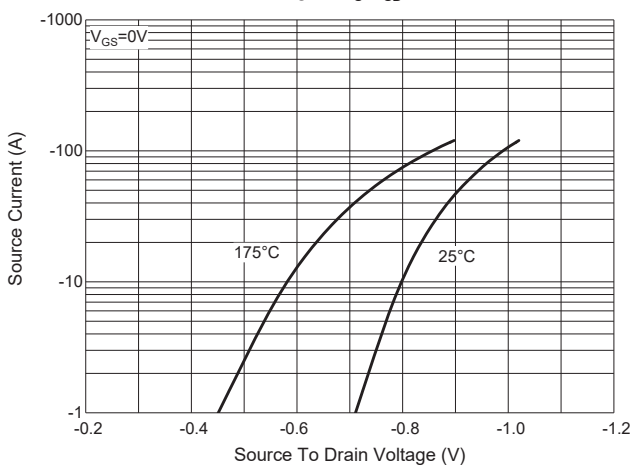


Fig. 10 - Drain Current

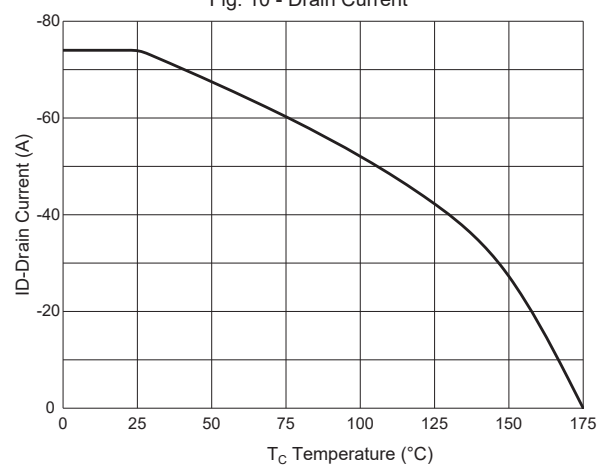
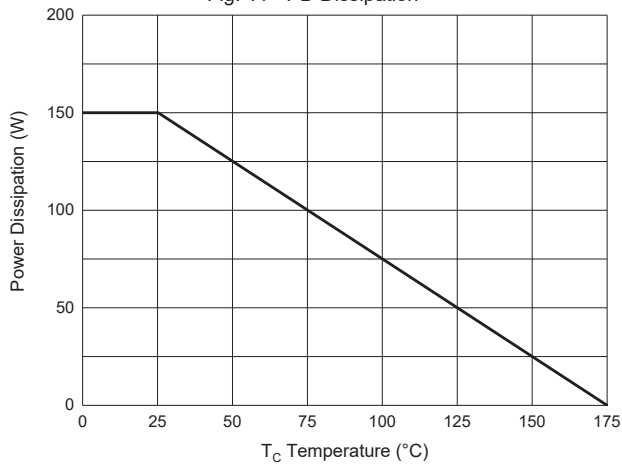


Fig. 11 - PD Dissipation



Curve Characteristics

Fig. 12 - Safe Operation Area

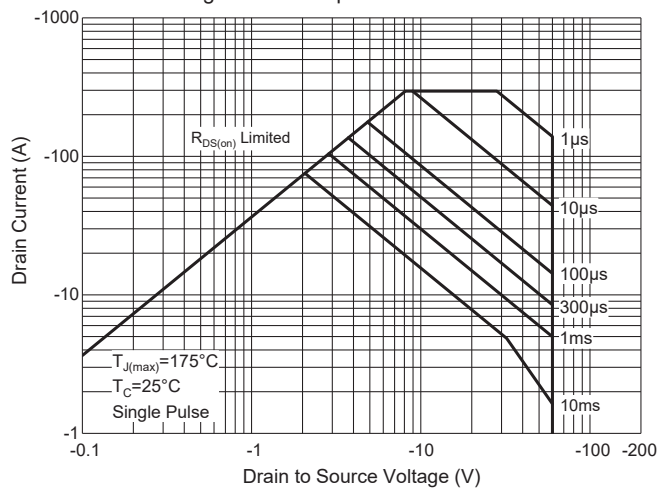
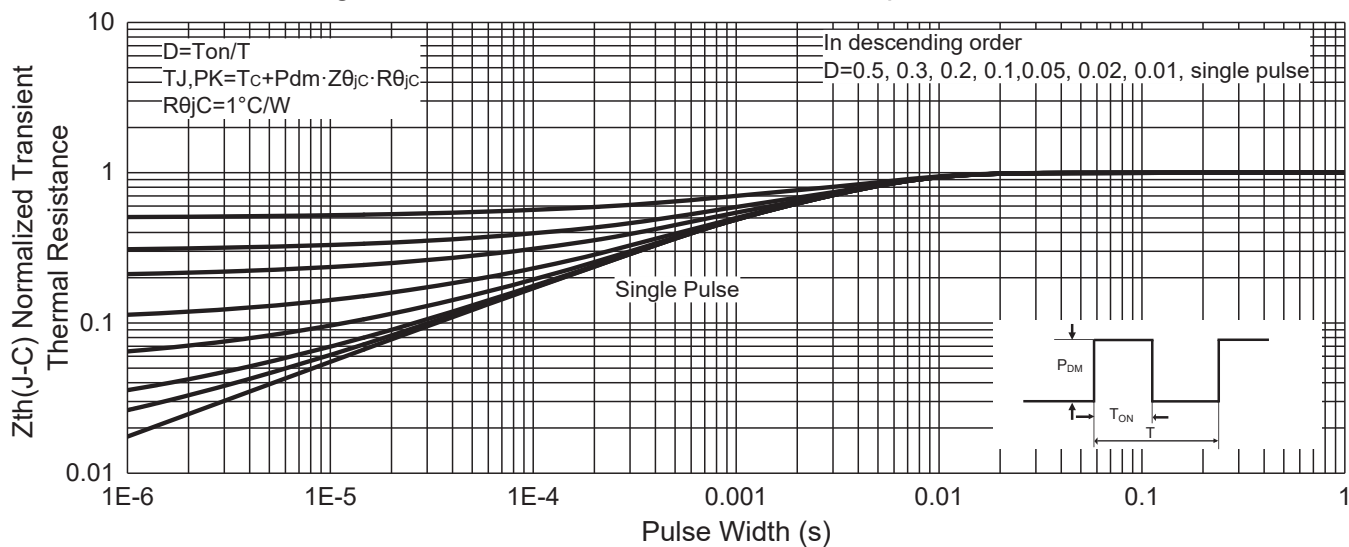


Fig. 13 - Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 5Kpcs/Reel

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